

Nch 100V 20A Power MOSFET

V_{DSS}	100V
R _{DS(on)} (Max.)	46m $Ω$
I _D	20A
P_D	20W

● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

Application

Switching Power Supply

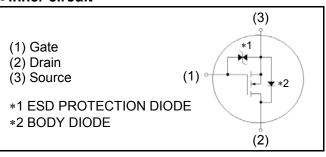
Automotive Motor Drive

Automotive Solenoid Drive

Outline

CPT3 (SC-63) <SOT-428>

●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	201N10

● Absolute maximum ratings(T_a = 25°C)

Paramete	Parameter			Unit
Drain - Source voltage	V_{DSS}	100	V	
Continuous drain surrent	T _c = 25°C	I _D *1	±20	А
Continuous drain current	T _c = 100°C	I _D *1	±10	А
Pulsed drain current	I _{D,pulse} *2	±80	А	
Gate - Source voltage		V_{GSS}	±20	V
Avalanche energy, single pulse		E _{AS} *3	14.6	mJ
Avalanche current		I _{AR} *3	10	А
D	T _c = 25°C	P _D	20	W
Power dissipation $T_a = 25^{\circ}C$		P _D	0.85	W
Junction temperature		T _j	150	°C
Range of storage temperature		T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Symbol	Min.	Тур.	Max.	UTIIL
Thermal resistance, junction - case	R_{thJC}	-	-	6.25	°C/W

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	100	ı	ı	V
		V _{DS} = 100V, V _{GS} = 0V			1	
Zero gate voltage drain current		T _j = 25°C	-	-	ı	μΑ
		V _{DS} = 100V, V _{GS} = 0V		-	100	
		T _j = 125°C	-			
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μΑ
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	1.0	-	2.5	V
		$V_{GS} = 10V, I_D = 20A$	-	33	46	
Static drain - source on - state resistance	D *4	$V_{GS} = 4.0V, I_D = 20A$	-	36	50	m()
	$R_{DS(on)}$	V _{GS} = 10V, I _D = 20A		60	0.4	mΩ
		T _j = 125°C	-	60	84	
Forward transfer admittance	9 _{fs}	$V_{DS} = 10V, I_{D} = 20A$	15	30	-	S

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions		Unit		
r ai ai ii etei	Symbol Conditions –		Min.	Тур.	Max.	Offic
Input capacitance	C_{iss}	V _{GS} = 0V	-	2100	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	180	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	120	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 50V$, $V_{GS} = 10V$	-	100	-	
Rise time	t _r *4	I _D = 10A	-	35	-	ne
Turn - off delay time	${\rm t_{d(off)}}^{*4}$	$R_L = 12\Omega$	-	150	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	100	-	

●Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Offic
Total gate charge	Qg *4	$V_{DD} \simeq 50V$	-	55	-	
Gate - Source charge	Q _{gs} *4	I _D = 20A	-	5.5	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 10V	-	12.5	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 30V$, $I_D = 20A$	-	2.7	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Symbol Conditions -		Тур.	Max.	Offic
Continuous source current	l _S *1	T _c = 25°C	-	ı	14	Α
Pulsed source current	I _{SM} *2	1 c = 23 G	-	-	80	Α
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V
Reverse recovery time	t _{rr} *4	I _S = 20A	-	65	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	144	-	μС

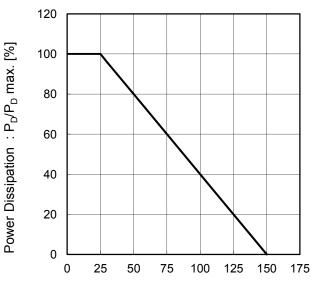
^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L \simeq 100 μ H, V_{DD} = 50V, Rg = 10 Ω , starting T_j = 25°C

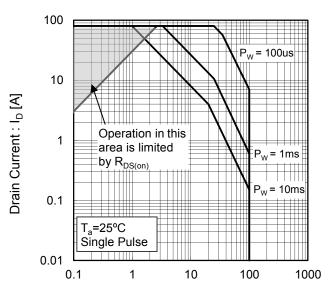
^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve



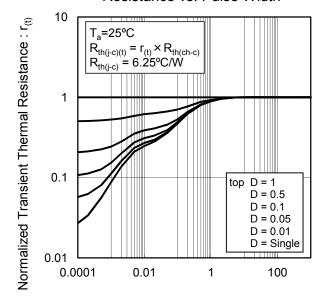
Junction Temperature : T_i [°C]

Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

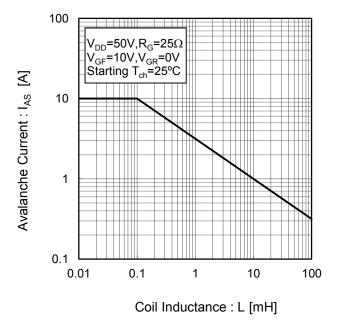
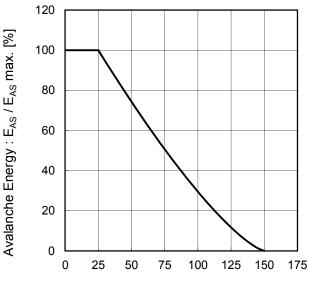
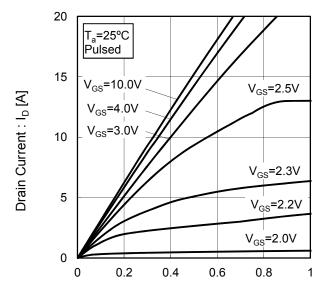


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



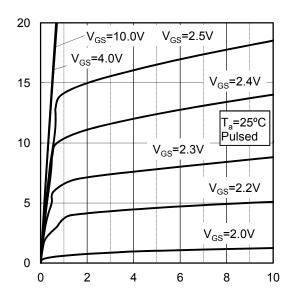
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

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•Electrical characteristic curves

Fig.8 Breakdown Voltage vs. Junction Temperature 120 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 115 $I_D = 1mA$ 110 105 100 95 90 85 80 -50 0 50 100 150 Junction Temperature : T_i [°C]

100
V_{DS}= 10V

10
T_a= 125°C
T_a= 75°C
T_a= 25°C
T_a= -25°C
T_a= -25°C

0.001

0

Fig.9 Typical Transfer Characteristics

Gate - Source Voltage : V_{GS} [V]

Fig.11 Transconductance vs. Drain Current

3

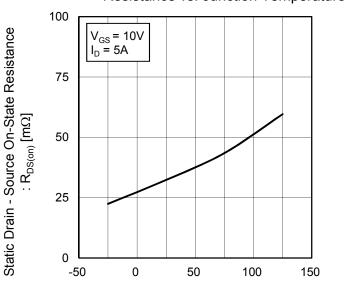
Fig.10 Gate Threshold Voltage vs. Junction Temperature 3.0 V_{DS} = 10V Gate Threshold Voltage: V_{GS(th)} [V] 2.5 $I_D = 1 \text{mA}$ 2.0 1.5 1.0 0.5 0.0 -50 -25 0 25 50 75 100 125 150 Junction Temperature : T_i [°C]

100
V_{DS}= 10V
T_a= -25°C
T_a=25°C
T_a=75°C
T_a=125°C
T_a=125°C
T_a=125°C
T_a=125°C

Drain Current : I_D [A]

Fig.12 Static Drain - Source On - State Fig.13 Static Drain - Source On - State Resistance vs. Gate Source Voltage Resistance vs. Drain Current(I) 100 100 Static Drain - Source On-State Resistance T_a=25°C Static Drain - Source On-State Resistance T_a=25°C 75 V_{GS}= 4.5V $I_D = 10A$ V_{GS}= 4.0V $:R_{\text{DS(on)}}\left[\text{m}\Omega\right]$ $:R_{\text{DS(on)}}\left[\text{m}\Omega\right]$ $I_{D} = 20A$ 50 25 0 10 0 5 10 15 0.01 0.1 10 100 Gate - Source Voltage : V_{GS} [V] Drain Current : I_D [A]

Fig.14 Static Drain - Source On - State
Resistance vs. Junction Temperature



Junction Temperature : T_j [°C]

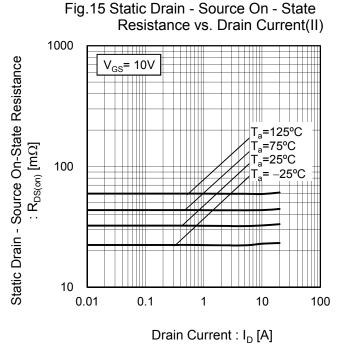


Fig.16 Static Drain-Source On-State
Resistance vs. Drain Current(III)

1000

V_{GS}= 4.5V

T_a=125°C

T_a=75°C

T_a=25°C

T_a=-25°C

T_a=-25°C

T_a=-25°C

T_a=-25°C

T_a=-25°C

T_a=-25°C

T_a=-25°C

Fig.17 Static Drain - Source On - State
Resistance vs. Drain Current(IV)

1000

V_{GS}= 4.0V

T_a=125°C

T_a=75°C

T_a=25°C

T_a=25°C

T_a=25°C

T_a=25°C

T_a=25°C

T_a=125°C

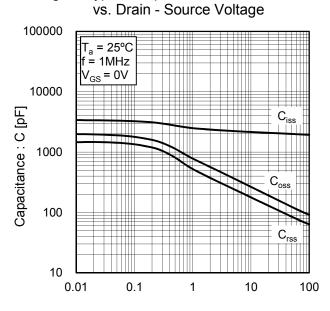
T_a

120 100 Drain Current Dissipation : I_D/I_D max. (%) 80 60 40 20 0 25 50 75 100 125 0 150 175

Junction Temperature : T_i [°C]

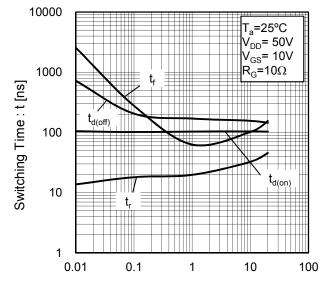
Fig.18 Drain Current Derating Curve

Fig.19 Typical Capacitance



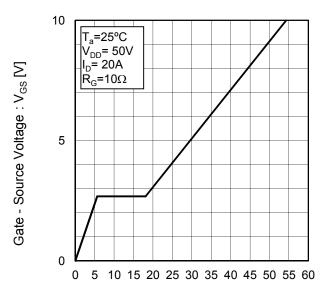
Drain - Source Voltage : V_{DS} [V]

Fig.20 Switching Characteristics



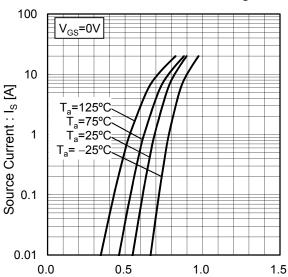
Drain Current : I_D [A]

Fig.21 Dynamic Input Characteristics

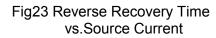


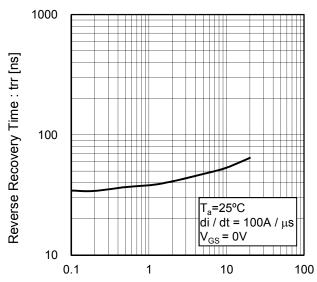
Total Gate Charge : Q_q [nC]

Fig.22 Source Current vs. Source - Drain Voltage



Source-Drain Voltage : V_{SD} [V]





Source Current : I_S [A]

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

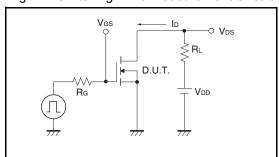


Fig.2-1 Gate Charge Measurement Circuit

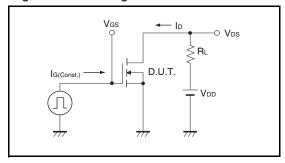


Fig.3-1 Avalanche Measurement Circuit

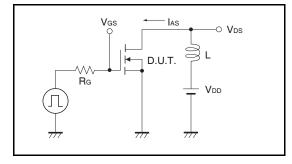


Fig.1-2 Switching Waveforms

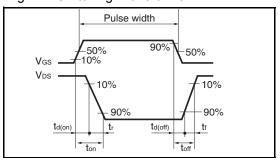


Fig.2-2 Gate Charge Waveform

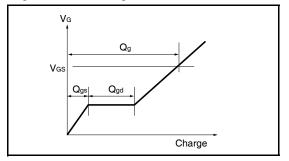
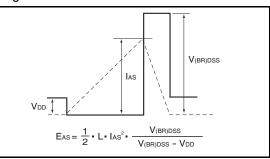
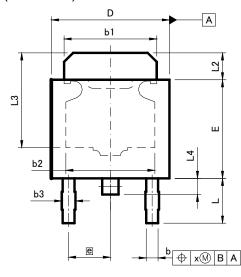


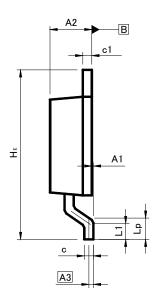
Fig.3-2 Avalanche Waveform

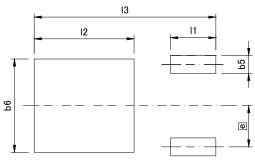


●Dimensions (Unit : mm)









DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.15	0	0.006
A2	2.20	2.50	0.087	0.098
A3	0.	25	0.	01
b	0.55	0.75	0.022	0.03
b1	5.00	5.30	0.197	0.209
b2	5.	00	0.	20
b3	0.	75	0.	03
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.30	6.70	0.248	0.264
Е	5.40	5.80	0.213	0.228
е	2.	30	0.	09
HE	9.00	10.00	0.354	0.394
L	2.20	2.80	0.087	0.11
L1	0.80	1.40	0.031	0.055
L2	1.20	1.80	0.047	0.071
L3	5.	5.30		.09
L4	0.	90	0.0	35
Lp	1.00	1.60	0.039	0.063
х	_	0.25	_	0.01

	1 471 71 4	ETERO	INOUEC		
DIM	DIM MILIME		INCHES		
DIM	MIN	MAX	MIN	MAX	
b5	_	1.00	_	0.04	
b6	_	5.20	-	0.205	
11	-	2.50	-	0.098	
12	_	5.50	_	0.217	
13	_	10.00	_	0.394	

Dimension in mm/inches

Notice

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSⅢ
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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